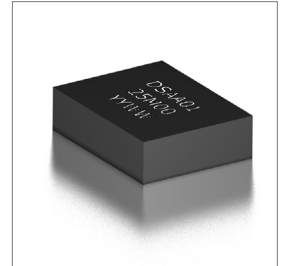
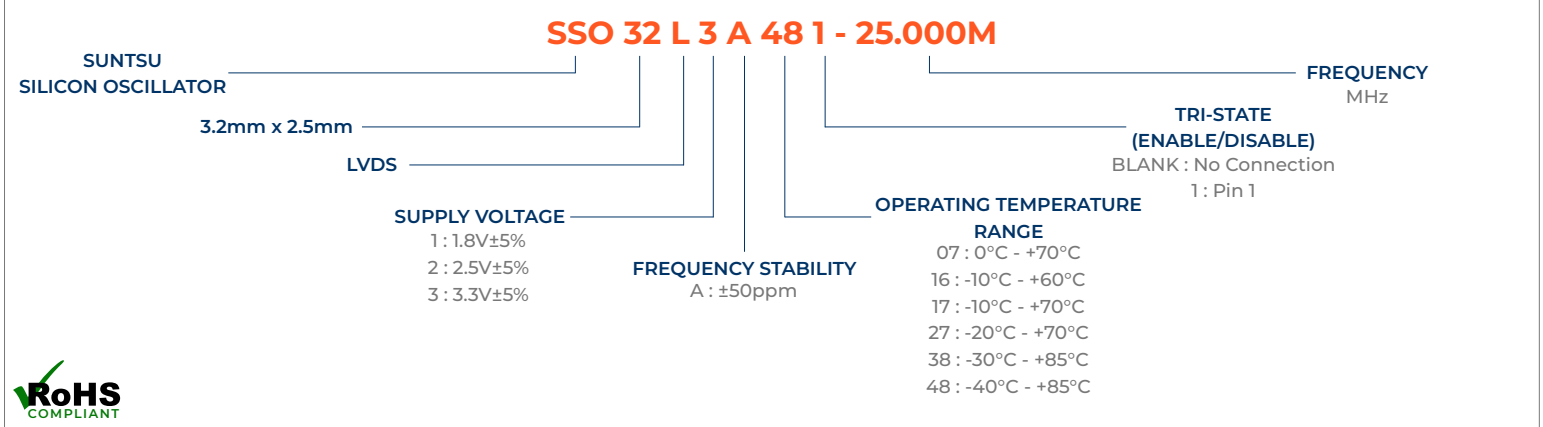


Features
• ± 50 ppm (Frequency Stability) Available
• All Silicon without Quartz and MEMS
• LVDS Output
• Low Jitter
• Built in LDO and Power Filter Circuit
• Moisture Sensitivity Level 2

Applications
• Intelligent Terminal
• Ethernet
• Consumer Electronics
• Communication Equipment



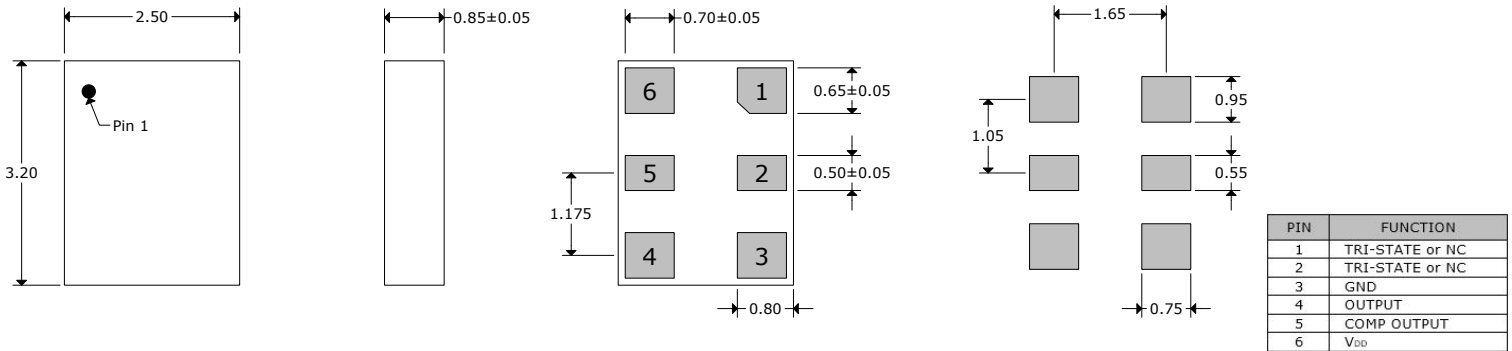
Part Numbering Guide



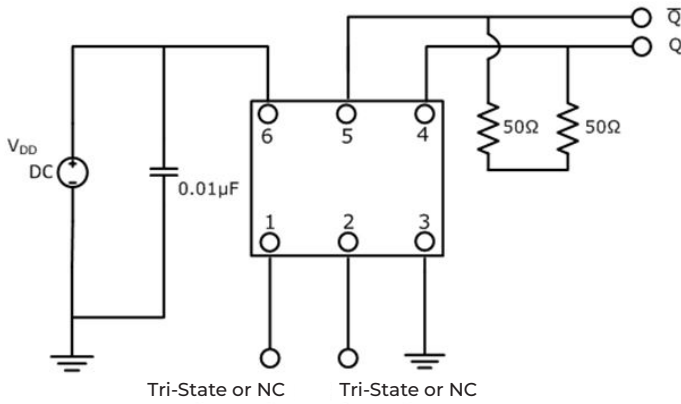
Electrical Parameters	Units	Minimum	Typical	Maximum	Remarks
Frequency Range	MHz	0.01		350	
Frequency Stability (Includes Initial Tolerance at 25°C, Frequency Stability over Operating Temperature, Output Load Change, Supply Voltage Change, and Ten Years Aging at 25°C.)	ppm	-50		50	
Operating Temperature	°C	-40		85	See part numbering guide for options
Storage Temperature	°C	-55		105	
Supply Voltage (V _{DD}) - 1.8V option	V	1.71	1.8	1.89	
Supply Voltage (V _{DD}) - 2.5V option	V	2.375	2.5	2.625	
Supply Voltage (V _{DD}) - 3.3V option	V	3.135	3.3	3.47	
Current (I _{DD}) - 1.8V to 3.3V	mA		45	55	
Output Load (LVDS)	Ω			100	
Common Mode Voltage of Diff. Output (V _{oc})	V	0.795	0.85	0.905	1.8V Option
Common Mode Voltage of Diff. Output (V _{oc})	V	1.125	1.20	1.275	2.5V & 3.3V
Output Voltage Low	mV	0	5	10	
Differential Output Voltage (V _{OD})	V	0.5	0.82	0.96	
Differential Output Error (ρ V _{OD})	mV			50	
Offset Voltage (V _{OS})	V	1.125	1.250	1.375	
Offset Error (ρ V _{OS})	mV			50	
Rise (TR) and Fall (TF) Time	ps			350	
Symmetry (Duty Cycle)	%	45	50	55	
Tri-State Input Voltage - Enable	V	0.7*V _{DD}			No Connection
Tri-State Input Voltage - Disable	V			0.3*V _{DD}	
Start-Up Time	ms			4	
Phase Jitter (12kHz ~ 20MHz)	ps		0.35	1	

Outline Drawing & Land Pattern

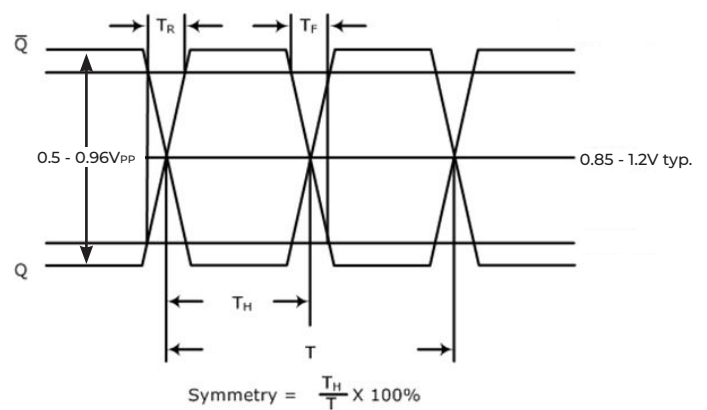
All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



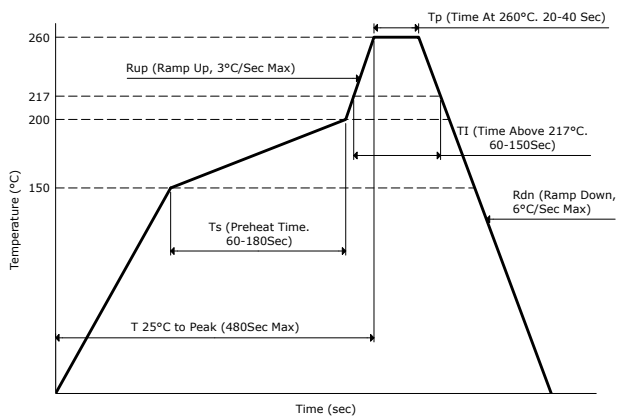
Test Circuit (LVDS)



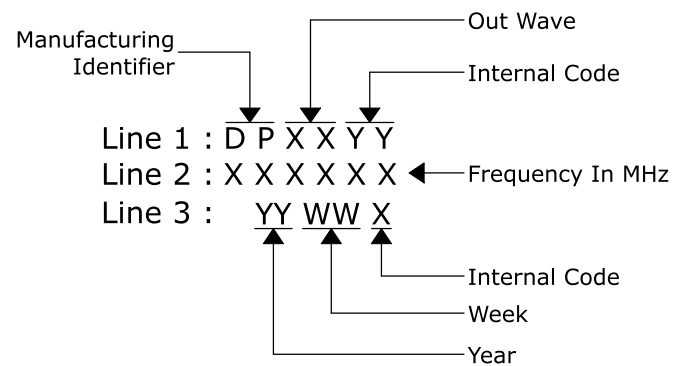
Waveform (LVDS)



Reflow Profile



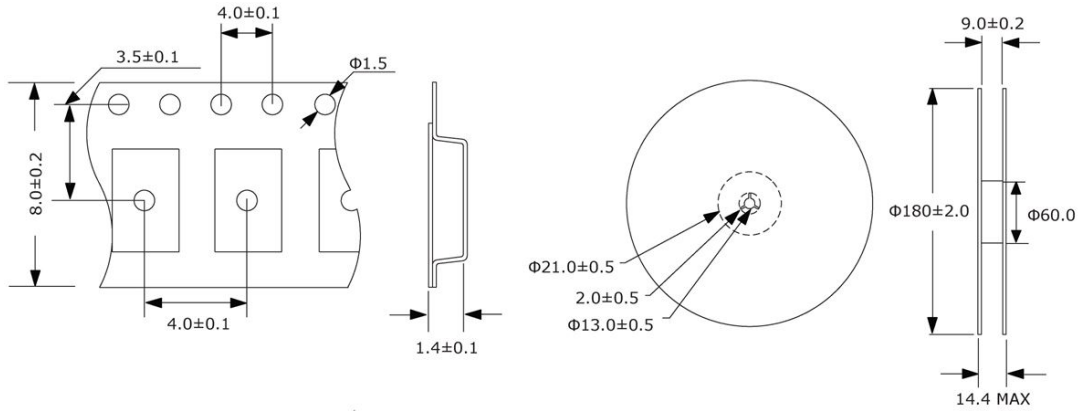
Part Marking



Tape And Reel Dimensions

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.

2,500pcs/Reel



Environmental Specifications

Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Solderability	MIL-STD-883, Method 2003
Moisture Sensitivity	J-STD-020, MSL 2

Mechanical Specifications

Mechanical Shock	MIL-STD-202, Method 213, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Resistance to Solvents	MIL-STD-202, Method 215
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K